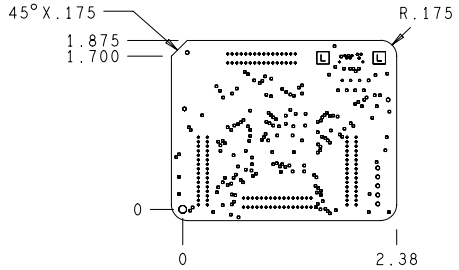
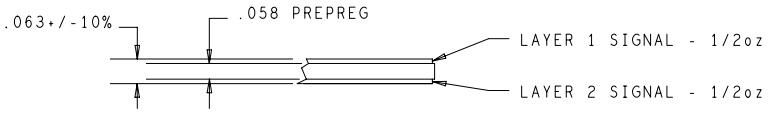
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	ALPHA RELEASE	2/26/08	DFK
2	BETA RELEASE	7/11/08	DFK
**	PRODUCTION RELEASE	4/6/09	DFK
*A	PRODUCTION RELEASE	8/6/09	DFK





DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	8.0	+3.0/-8.0	PLATED	11
◦	10.0	+3.0/-10.0	PLATED	177
•	28.0	+3.0/-3.0	PLATED	128
◦	40.0	+3.0/-3.0	PLATED	5
◦	43.0	+3.0/-3.0	PLATED	3
⌶	172.0	+3.0/-3.0	PLATED	2
•	28.0	+3.0/-3.0	NON-PLATED	2
○	85.0	+3.0/-3.0	NON-PLATED	1

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER 1 oz. EXTERNAL LAYERS AND 1 oz. COPPER FOIL FOR INTERNAL LAYER 2. USE 3 oz. COPPER FOR INTERNAL LAYER 3.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 TOL. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO ETCH DATE CODE AND LOGO ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLUE**
7. FINISH:
   A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0), DATE CODE (WWYY), AND RoHS COMPILANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .010 in/in.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN INCHES	DRAWN DFK	8/6/09
TOLERANCES ON; ANGLES +/- 2°	CHECKED	
2 PL DECIMALS +/- .010	ENGRG DFK	8/6/06
3 PL DECIMALS +/- .005	ISSUED	
THIRD ANGLE PROJECTIONS		

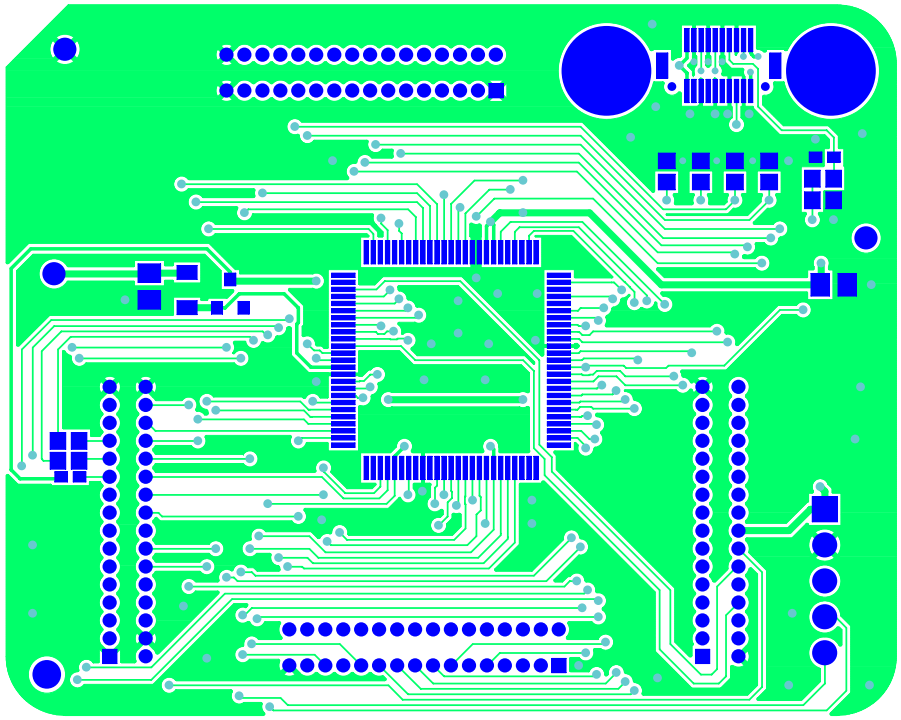
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FABRICATION DRAWING
CY8C29 FAMILY
PROCESSOR MODULE

SIZE	FSCM NO	DWG NO	REV
C		PDCR-9464	*A

SCALE: 1/1 SHEET: 1 OF 1



PDCR-9464 REV *A PRIMARY SIDE

PDCR-9464 REV *A SECONDARY SIDE